

## *SOKUDO*



# 32nm Lithography: Evolution or Revolution

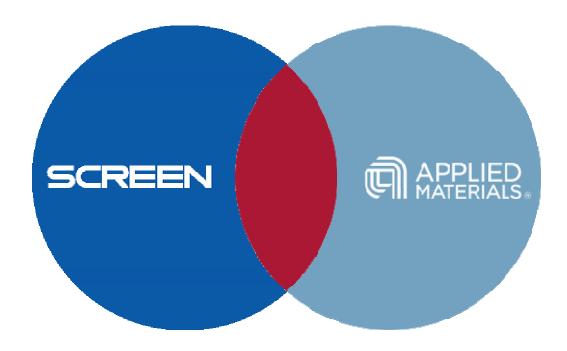
for Coat/Develop Track Equipment

**SOKUDO Co., Ltd.** 





#### Joint Venture Company as of July 20, 2006



50KUD0



### **Centers for Research & Development**



*50KUD0* 

#### **White Canvas RAKUSAI**

120nm CD Nikon S302A (NA 0.65)

#### **Maydan Technology Center**

65nm CD ASML XT:1400 (NA 0.93)





## **Immersion Lithography Development Site**



**ASML Veldhoven** 

45nm CD ASML XT:1700Fi (NA 1.2)





#### **32nm Lithography Development Options**

#### Immersion EVOLUTION

**►** ASML, Nikon, and/or Canon process co-development early access to ArF immersion NA > 1.3 exposure

#### Extreme REVOLUTION (EUV)

SELETE (Tsukuba, Japan) EUV Project

#### REVOLUTIONARY EVOLUTION (E-Beam)

**■** e-BEAM Corporation (Tokyo, Japan) cooperation via Dainippon Screen Mfg. Co., Ltd. participation



## Early EUVL Sampling at ASML Veldhoven

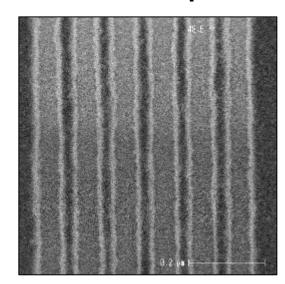
EUV Coat, Develop, and PEB by



Resist: MET-2D, ~18 mJ/cm<sup>2</sup>
ASML EUV Alpha NA=0.25

σ= 0.5 (conventional illumination)
no process optimization development

50 nm half-pitch



#### 40 nm half-pitch

